EPEPS is the premier international conference on advanced and emerging issues in electrical modeling, measurement, analysis, synthesis, and design of electronic interconnections, packages, and systems. It also focuses on new methodologies and CAD/design techniques for evaluating signal, power, and thermal integrity and ensuring performance in high-speed, RF, and wireless designs. EPEPS is jointly sponsored by IEEE Electronics Packaging Society, IEEE Microwave Theory and Techniques Society and IEEE Antennas and Propagation Society. Submitted papers should describe new technical contributions related to the area of electrical performance of high-performance interconnect systems, covering:

- System-level, board-level, package-level and on-chip interconnects
- High-speed channels, links, backplanes, serial and parallel interconnects, SerDes
- RF/microwave/mm-wave packaging structures and components, antenna-in-package and RFIC co-design, mixed signal modules and wireless switches
- Signal and thermal integrity
- Power integrity and power distribution networks
- Low power mobile and personal applications
- Memory and DDR interfaces
- Jitter and noise management
- Electronic packages and microsystems
- Heterogeneous integration, 2.5D/3D interconnects and packages, TSVs and MCMs
- Electromagnetic (EM) and EM interference modeling, simulation algorithms, tools, and flows
- Macromodeling and model order reduction as it applies to electrical analysis
- Advanced and parallel CAD techniques for signal, power, and thermal integrity analysis
- Measurement and data analysis techniques for system-level and on-chip structures.

Submission Deadline: July 15, 2018, 8 p.m. Pacific Time

Conference Chairs:
Xiaoxiong Gu (IBM Research) xgu@us.ibm.com
Roni Khazaka (McGill University) roni.khazaka@mcgill.ca

For more information/contact: epeps-admin@illinois.edu

Submission Format: 2-column, 3-page PDF format only. Selected papers will be invited for a special issue in IEEE Transactions on Components, Packaging, and Manufacturing Technology. Information for authors can be found at www.epeps.org. Submitted manuscripts should be camera ready and compliant with the general standards of the IEEE, including appropriate referencing. Noncompliant manuscripts will not be considered for review.

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Tutorials: EPEPS offers tutorials on state-of-the-art topics during the conference.

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